

Stressless Thermal Putty Gel / XK-G40

Introduction

Syringes packaging, automated production, high temperature resistance, and 100% thermal curing putty. XK-G series is a silicone based, high performance thermal Gel, filling with a variety of high-performance ceramic powder. High thermal conductivity, low thermal resistance, good insulation, infinite compression. stressless application especially for UAV.

Features

Especially for UAV design
 Excellent compressibility
 Low thermal resistance
 Best for north bridge IC

Applications

Consumer electronics/Automotive systems
 UAV/ Telecommunications
 Hand-set applications



	Unit	XK-G40	Method
Color		Blue	visual
Flow Rate (30cc EFD cartridges 0.100" orifice 90psi)	g/min	6	
Specific Gravity	g/cm ³	3.2	ASTM D792
Volume Resistivity	Ωcm	>10 ¹³	ASTM D257
Thermal Conductivity	W/mK	4.0	HOT DISK
Breakdown Voltage	KV/mm	8	ASTM D149
Dielectric Constant	1	8.0	ASTM D150
BLT Thickness	mm	0.09	ASTM D374
Application temperature	°C	-50~200	
shelf life	month	12	
Siloxane Volatiles D4~D20	%	<0.01	GC-FID
Coefficient of Thermal Expansion,	ppm/K	140	
Flammability	UL94	V-0	UL94